

43. (New) The interface material of claim 41, wherein the interface material further comprises at least one wetting enhancer.
44. (New) The interface material of claim 41 wherein the at least one resin material comprises a silicone resin.
45. (New) The interface material of claim 43, wherein the silicone resin comprises a vinyl terminated siloxane, a reinforcing additive, a crosslinker and a catalyst.
46. (New) The interface material of claim 44, wherein the vinyl terminated siloxane is vinyl silicone.
47. (New) The interface material of claim 44, wherein the reinforcing additive is vinyl Q resin.
48. (New) The interface material of claim 44, wherein the crosslinker comprises a hydride functional siloxane.
49. (New) The interface material of claim 44, wherein the catalyst comprises a platinum complex.
50. (New) The interface material of claim 8, wherein the platinum complex is a platinum-vinylsiloxane compound.
51. (New) The interface material of claim 42, wherein the wetting enhancer comprises an organo-titanite compound.
52. (New) The interface material of claim 41, wherein the at least one solder material comprises an indium-based alloy or compound.
53. (New) The interface material of claim 11, wherein the indium-based alloy or compound comprises InSn, InAg or In.
54. (New) The interface material of claim 41, wherein the at least one solder material comprises a tin-based alloy or compound.
55. (New) The interface material of claim 43, wherein the tin-based alloy or compound comprises SnAgCu or SnBi.

56. (New) The interface material of claim 41, wherein the interface material comprises one of an aluminum or an aluminum-based alloy or compound.
57. (New) The interface material of claim 41, further comprising a filler material..
58. (New) The interface material of claim 56, wherein the filler material comprises carbon microfibers.
59. (New) The interface material of claim 41, wherein the at least one resin material is also crosslinkable.
60. (New) The interface material of claim 42, wherein the at least one solder material is present in an amount of at least about 60 weight percent.
61. (New) The interface material of claim 60, wherein the at least one solder material is present in an amount of at least about 70 weight percent.
62. (New) The interface material of claim 61, wherein the at least one solder material is present in an amount of at least about 80 weight percent.
63. (New) A layered material comprising the interface material of claim 41.
64. (New) A layered material comprising the interface material of claim 42.

IN THE SPECIFICATION

Insert the following before "Field of the Invention":

This application is a divisional of allowed application Serial Number 09/851103, filed May 7, 2001.

REMARKS

No new matter was added by this preliminary amendment.

Please use JM35978 (CIP2) DIV – 4962 as the docket number for this application.